



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

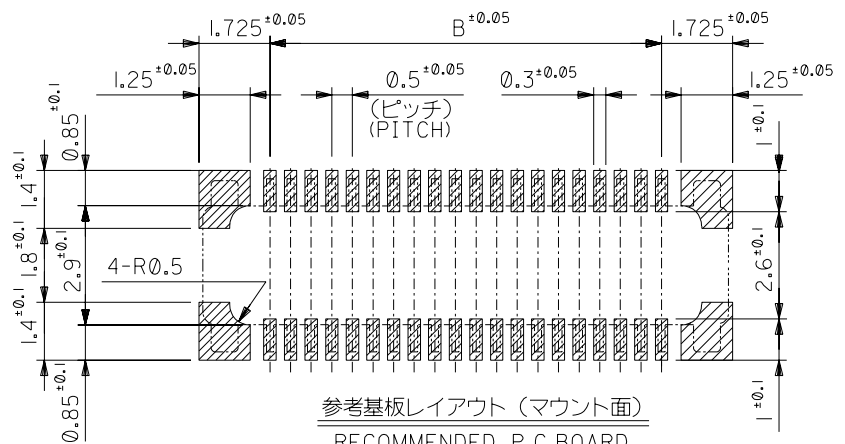
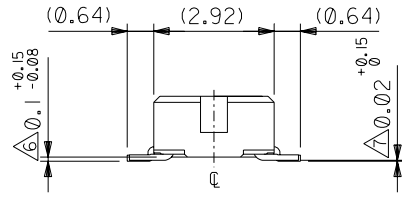
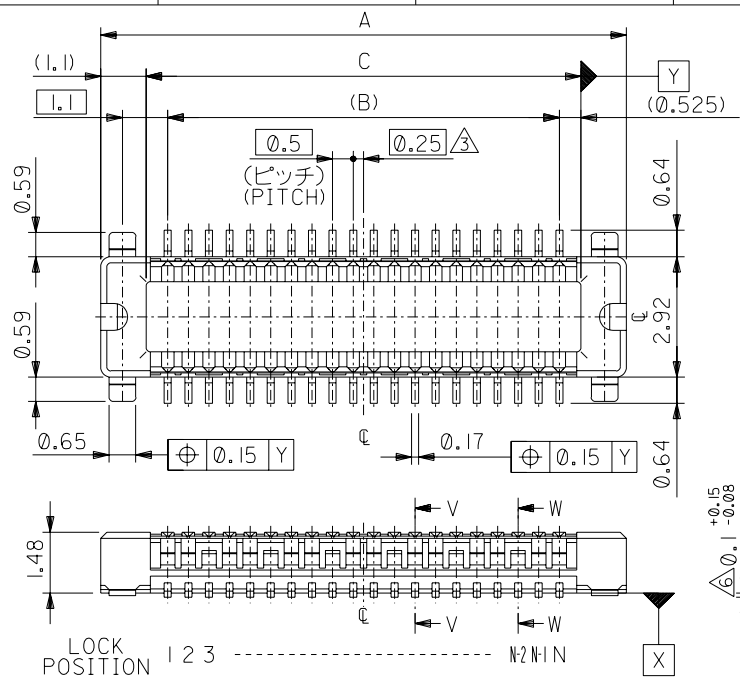
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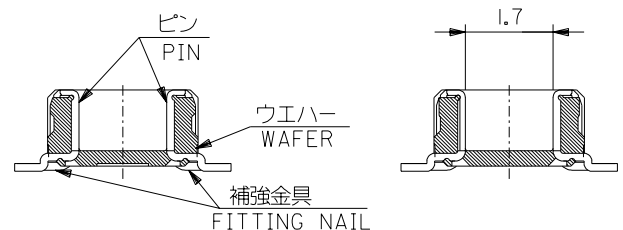
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



DWG. NO.
SD-53949-006

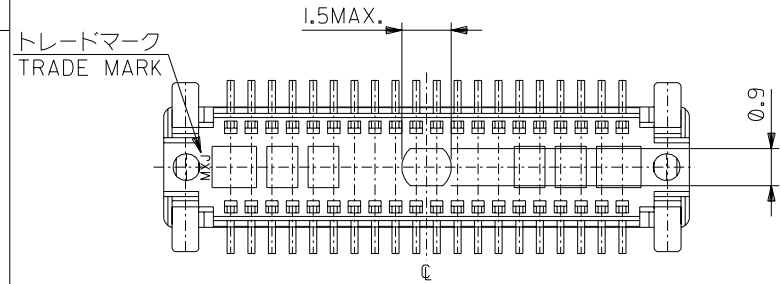


参考基板レイアウト (マウント面)
RECOMMENDED P.C. BOARD
PATTERN DIMENSION (REF.)
(MOUNTING AREA)



SECT.W-W(LOCK PART)

SECT.V-V(W/O LOCK PART)



NONE	20.55	19.5	22.75	53949-0871	80	
	18.05	17.0	20.25	53949-0771	70	
10,21	15.55	14.5	17.75	53949-0671	60	
53949-**71	4,10,16,22	13.05	12.0	15.25	53949-0571	50
MODEL NO.	LOCK POSITION	C	B	A	MATERIAL NO.	CIRCUIT

材料 MATERIAL		SHEET 2 OF 2 参照 REFER TO SHEET 2 OF 2		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
仕上げ FINISH		//		REVISE ONLY ON CAD SYSTEM	
適用電線範囲 WIRE RANGE		//		TITLE 名称	
被覆外径 INS. RANGE		//		0.5 B-To-B PLUG Assy WITH NAIL (Hgt=2.5) -LEAD FREE-	
角度 ANGLE	±3°	DRAWN BY	04/02/16 H.KAWABATA	CHK'D BY	04/02/16 K.TOJO
30以上 OVER	+0.3	DR.	04/02/16 M.SASAO	尺度 SCALE	//
10以上 OVER 30未滿 UNDER	+0.25	REVISION RECORD		DWG. NO.	SHEET 1 OF 2 REV
未滿 UNDER	+0.2	記号 LTR		SD-53949-006	0
一般公差 GENERAL TOLERANCES		新規作成 PROPOSED (J2004-2611)			

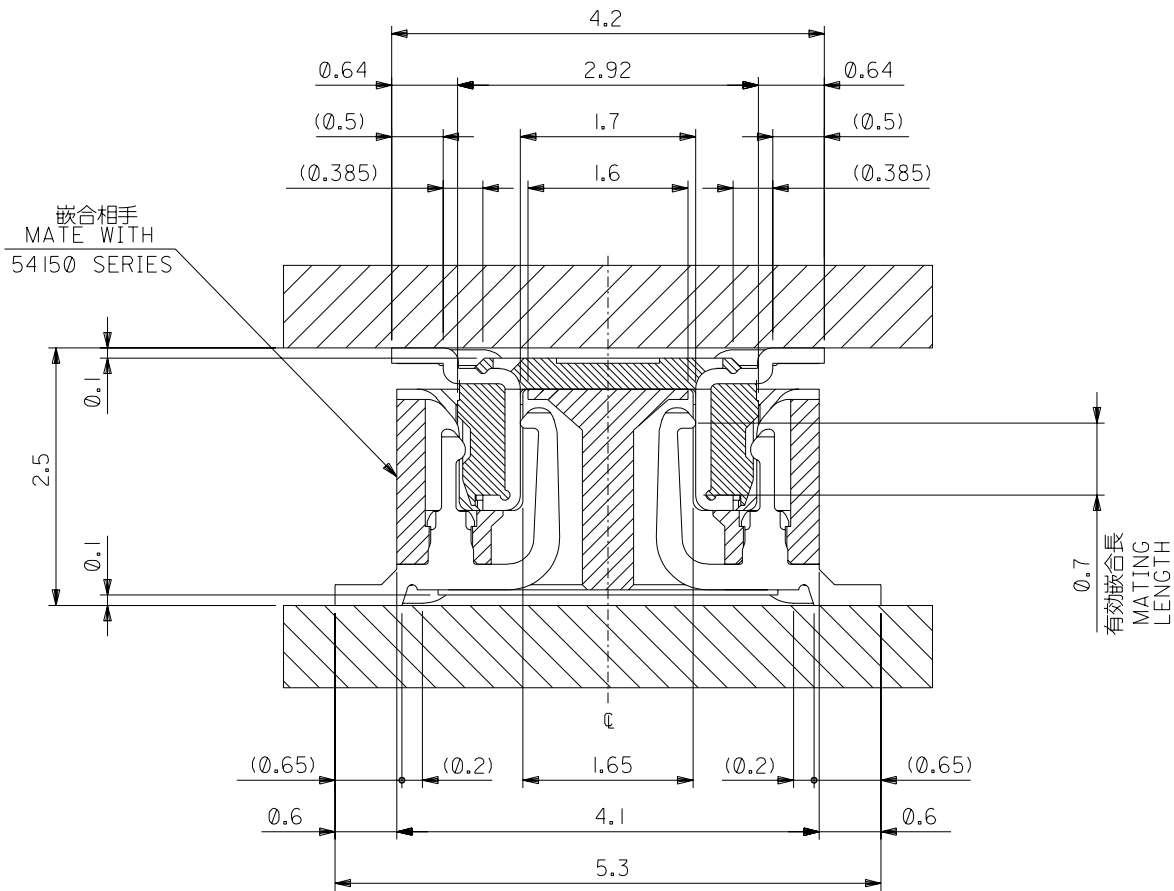
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DIMENSIONS IN METRIC DO NOT SCALE DRAWING

SD-53949-006.S01

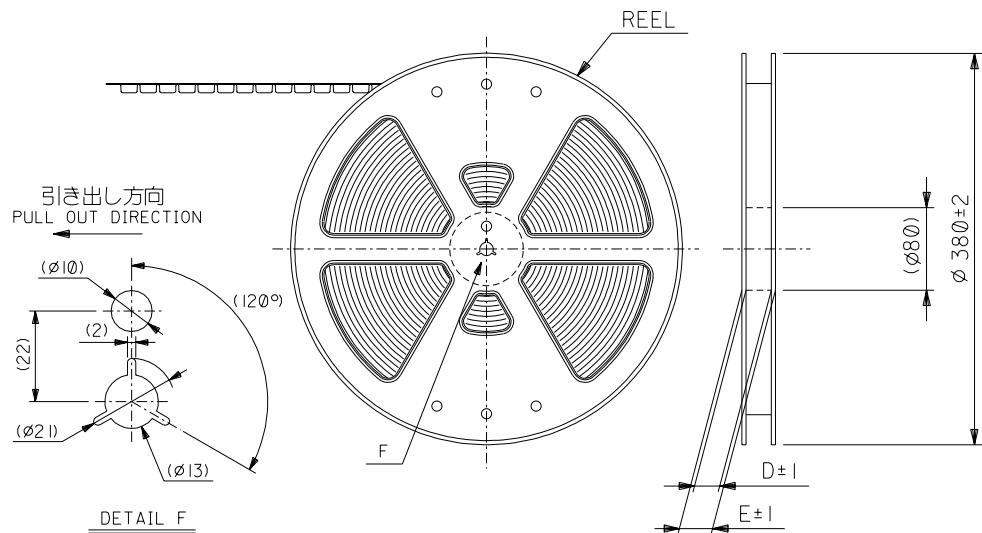
注記 NOTES:

- 1 使用材料 MATERIAL
 ハウジング: 液晶ポリマー (LCP) ガラス充填 UL94V-0 (黒)
 HOUSING : LIQUID CRYSTAL POLYMER (LCP)
 (GLASS FIELD)UL94V-0 (COLOR:BLACK)
 ターミナル: 黄銅 (t=0.15)
 TERMINAL : BRASS(t=0.15)
 補強金具: リン青銅 (t=0.15)
 FITTING NAIL : PHOSPHOR BRONZE(t=0.15)
- 2 メッキ仕様 PLATING
 コンタクト部: 金メッキ
 CONTACT AREA : GOLD 0.25 MICROMETER MINIMUM
 テール部: 金メッキ
 TAIL AREA:GOLD 0.4 MICROMETER MINIMUM
 ターミナル部下地メッキ: ニッケルメッキ
 UNDER PLATING : NICKEL (TERMINAL AREA)
 1.5 MICROMETER MINIMUM
 補強金具: 錫メッキ
 FITTING NAIL : TIN 1.0 MICROMETER MINIMUM
 補強金具下地メッキ: ニッケルメッキ
 UNDER PLATING : NICKEL(FITTING NAIL)
 1.0 MICROMETER MINIMUM
 (全極数/2) = 偶数の場合に適用。
 APPLY FOR (CIRCUIT/2)=EVEN.
- 4 嵌合相手: 54150シリーズ。
 MATE WITH : 54150 SERIES.
- 5 テール及びネイルの平坦度は、0.1MAX。
 TAIL AND NAIL COPLANARITY TO BE 0.1MAX.
 テール部に適用。
 APPLY TO THE TAIL AREA.
 テールとネイルのズレ量。
 OFFSET BETWEEN TAIL AND NAIL.
 OFFSET BETWEEN TAIL AND NAIL.
8. 本製品は 53949-***I の鉛フリー品である。
 THIS PRODUCT IS LEAD FREE OF 53949-***I.



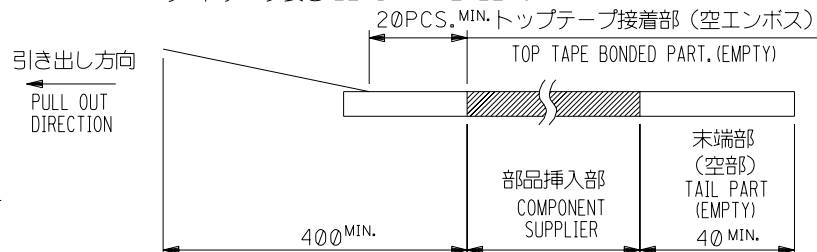
嵌合断面図 (参考)
MATED DRAWING (REF.)

角度 ANGLE		±3°	材料 MATERIAL		注記参照 SEE NOTES	MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
30以上 OVER		+0.3	仕上げ FINISH		//	
10以上 OVER 30 UNDER		+0.25	適用電線範囲 WIRE RANGE		//	TITLE 名称 0.5 B-To-B PLUG Assy WITH NAIL (Hg+=2.5) -LEAD FREE-
未満 10 UNDER		+0.2	被覆外径 INS. RANGE		//	DWG. NO. (SHEET 2 OF 2) REV SD-53949-006 0
一般公差 GENERAL TOLERANCES			記号 LTR	変更内容 REVISION RECORD	DR. CHK. DATE	DRAWN BY '04/02/16 H.KAWABATA CHK'D BY '04/02/16 K.TOJO APP'D BY '04/02/16 M.SASAO 尺度 SCALE //

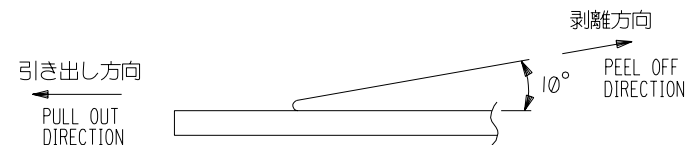


NOTES

- 製品詳細寸法については図面 SD-53949-006 を参照下さい。
RE DETAILED DIMENSION, SEE SD-53949-006.
- 梱包数量：3000個/リール
NUMBER OF CONNECTORS：3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：0.1~1.3N {10~130gf} (剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE：0.1~1.3N {10~130gf}
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.

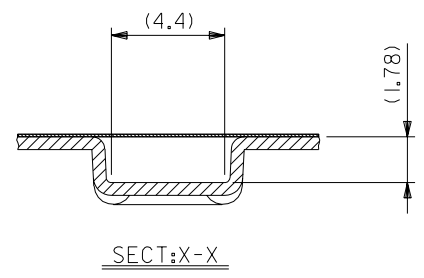
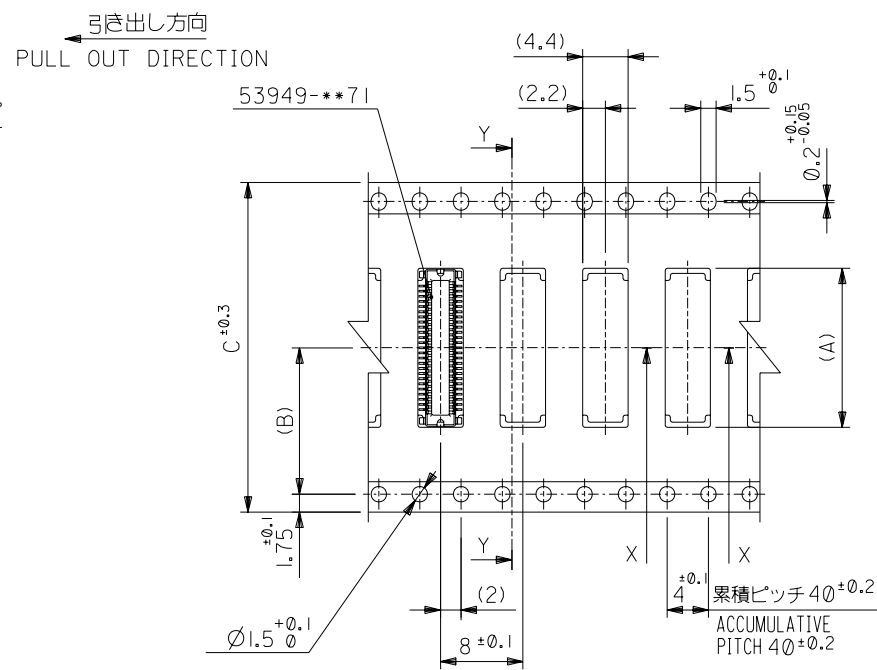
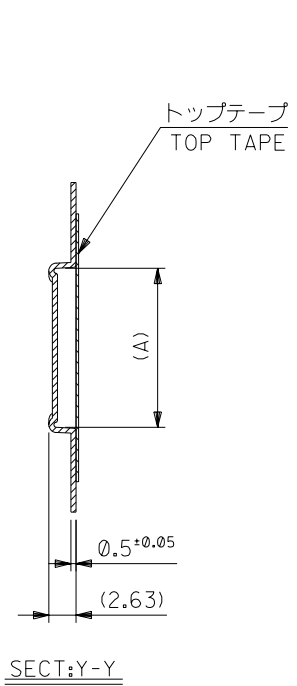


- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE)：ポリプロピレン (POLYPROPYLENE (PP))
トップテープ (TOPTAPE)：PET, PE, PEF
リール (REEL)：ポリスチレン (PS) (POLYSTYRENE (PS))
リサイクル材を含む (RECYCLE MATERIAL CONTAINED)
- 本製品は 53949-***8 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53949-***8.

				材料 MATERIAL		注記参照 SEE NOTES		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
				仕上げ FINISH		— # —		REVISE ONLY ON CAD SYSTEM	
角度 ANGLE		±3°		適用電線範囲 WIRE RANGE		— # —		TITLE 名称	
30 以上 OVER		+0.3		被覆外径 INS. RANGE		— # —		0.5 B-To-B PLUG Assy W/NAIL (Hgt=2.5) Embstp Pkg -LEAD FREE-	
10 以上 OVER 30 未満 UNDER		+0.25		DRAWN BY 04/02/16 H.KAWABATA		CHK'D BY 04/02/16 K.TOJO		DWG. NO. (SHEET 1 OF 3) REV	
10 未満 UNDER		+0.2		0 新規作成 PROPOSED (J2004-2611)		04/02/16		SD-53949-007 0	
一般公差 GENERAL TOLERANCES		記号 LTR		変更内容 REVISION RECORD		DR. CHK. DATE		M.SASAO 04/02/16 尺度 SCALE — # —	

DWC. NO. SD-53949-007
E
D
C
B
A
DIMENSIONS IN METRIC DO NOT SCALE DRAWING

8 7 6 5 4 3 2 1



32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE

53949-***78	32	37.4	33.4	32	14.2	20.45	53949-0778	70
						17.95	53949-0678	60
						15.45	53949-0578	50
MODEL NO.	CARRIER TAPE WIDTH	E	D	C	(B)	(A)	MATERIAL NO.	CIRCUIT
材料 MATERIAL SHEET 1 OF 3 参照 REFER TO SHEET 1 OF 3							molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
仕上げ FINISH							REVISE ONLY ON CAD SYSTEM	
適用電線範囲 WIRE RANGE							TITLE 名称	
被覆外径 INS. RANGE							0.5 B-To-B Conn PLUG Assy W/ NAIL Embst+p Pkg -LEAD FREE-	
DRAWN BY 04/02/16 H.KAWABATA							CHK'D BY 04/02/16 K.TOJO	
DR. 04/02/16 M.SASAO							DWG. NO. (SHEET 2 OF 3) REV	
尺度 SCALE							SD-53949-007 0	

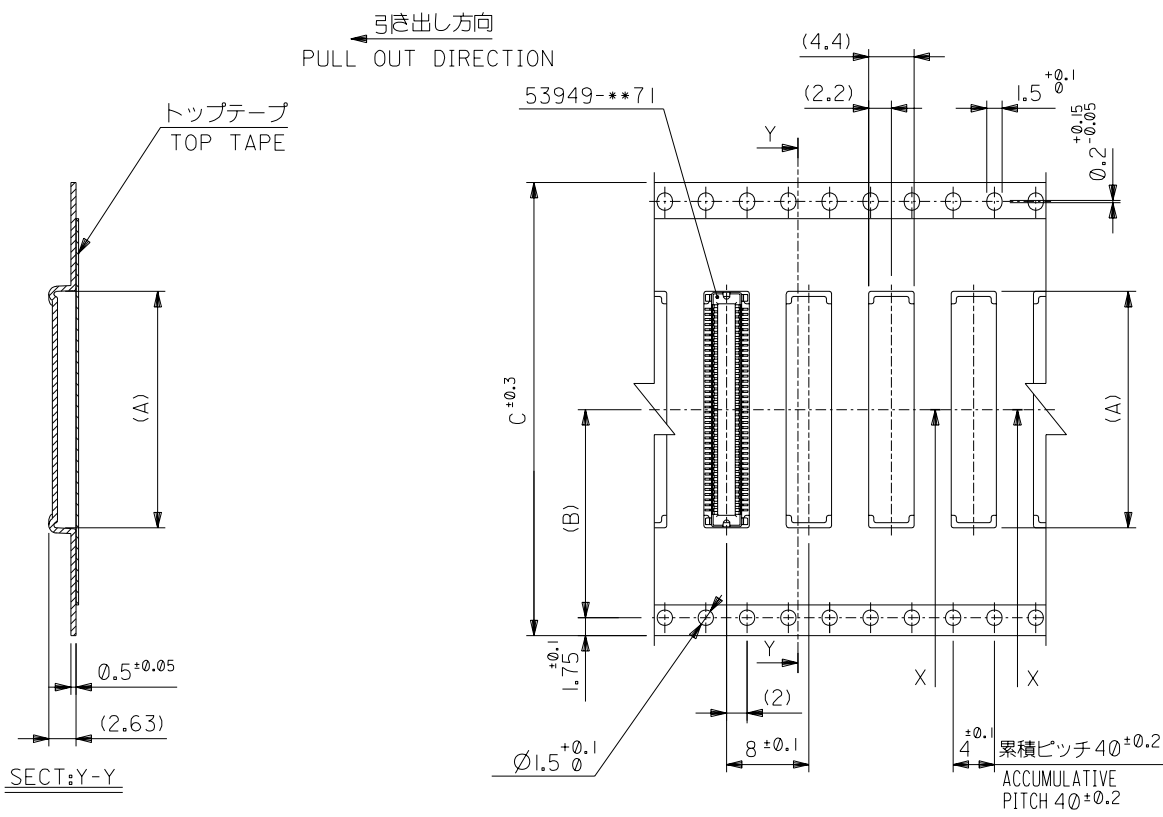
角度 ANGLE	±3°		
30以上 OVER	±0.5		
10以上 OVER 30 UNDER	±0.25		
未満 UNDER	±0.2		
一般公差 GENERAL TOLERANCES			

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8 7 6 5 4 3 2 1

SD-53949-007.S02

DWG. NO. SD-53949-007
 DIMENSIONS IN METRIC DO NOT SCALE DRAWING



44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE

53949-**78	44	49.4	45.4	44	20.2	22.95	53949-0878	80
MODEL NO.	キャリアテープ幅 CARRIER TAPE WIDTH	E	D	C	(B)	(A)	MATERIAL NO.	CIRCUIT
		材料 MATERIAL SHEET 1 OF 3 参照 REFER TO SHEET 1 OF 3				molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社		
		仕上げ FINISH				REVISE ONLY ON CAD SYSTEM		
		適用電線範囲 WIRE RANGE				TITLE 名称		
		被覆外径 INS. RANGE				0.5 B-To-B PLUG Assy W/NAIL (Hgt=2.5) Embstp Pkg -LEAD FREE-		
		DRAWN BY 04/02/16 H.KAWABATA	CHK'D BY 04/02/16 K.TOJO	DWG. NO. (SHEET 3 OF 3) REV				
		04/02/16	04/02/16	SD-53949-007 0				
		DR. M.SASAO	DATE					

角度 ANGLE	±3°
30 以上 OVER	±0.5
10 以上 OVER 30 未満 UNDER	±0.25
未満 UNDER	±0.2
一般公差 GENERAL TOLERANCES	

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